HALOGEN FREE





P-Channel 20-V (D-S) MOSFET

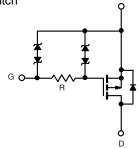
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)	
- 20	$0.060 \text{ at V}_{GS} = -4.5 \text{ V}$	- 4.5 ^a		
	$0.065 \text{ at V}_{GS} = -3.6 \text{ V}$	- 4.5 ^a	4.9 nC	
	0.080 at V _{GS} = - 2.5 V	- 4.5 ^a	4.9110	
	0.120 at V _{GS} = - 1.8 V	- 2		

FEATURES

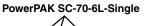
- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- New Thermally Enhanced PowerPAK® SC-70 Package
 - Small Footprint Area
 - Low On-Resistance
- Typical ESD Protection 2400 V
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

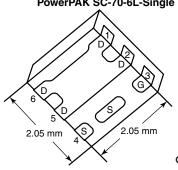
APPLICATIONS

· Load Switch and Battery Switch for Portable Devices



P-Channel MOSFET





ВМХ Part # code X X X ot Traceability and Date code

Marking Code

Ordering Information: SiA425EDJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS	S T _A = 25 °C, unle	ss otherwise not	ed	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 20	V	
Gate-Source Voltage		V_{GS}	± 12	v
	T _C = 25 °C		- 4.5 ^a	
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	I_	- 4.5 ^a	
Continuous Diain Current (1) = 150 °C)	T _A = 25 °C	I _D	- 4.5 ^{a, b, c}	
	T _A = 70 °C		- 4.5 ^{a, b, c}	Α
Pulsed Drain Current		I _{DM}	- 15	
Continuous Source-Drain Diode Current	T _C = 25 °C	I_	- 4.5 ^a	
Continuous Source-Diam Diode Current	T _A = 25 °C	ls –	- 2.4 ^{b, c}	
	T _C = 25 °C		15.6	
Maximum Power Dissipation	T _C = 70 °C	P _D	10	w
	T _A = 25 °C	' D	2.9 ^{b, c}	VV
	T _A = 70 °C		1.8 ^{b, c}	
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature) ^{d, e}			260	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 5 s	R _{thJA}	32	43	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	6	8]	

Notes:

- a. Package limited.
- b. Surface Mounted on 1" x 1" FR4 board.
- d. See Solder Profile (www.vishay.com/ppg?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 80 °C/W.

SiA425EDJ

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 15		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = - 230 μΑ		2.6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 4	μΑ	
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 8	mA	
Zoro Coto Voltago Droin Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10	- μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 10			Α	
_		V _{GS} = - 4.5 V, I _D = - 4.2 A		0.050	0.06		
		V _{GS} = - 3.6 V, I _D = - 4.0 A		0.053	0.065	1 _	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 3.6 A		0.065	0.080	Ω	
		V _{GS} = - 1.8 V, I _D = - 2 A		0.091	0.120		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 4.2 A		15		S	
Dynamic ^b				•			
Gate Resistance	R_{g}	f = 1 MHz	1.2	6	12	kΩ	
Turn-On Delay Time	t _{d(on)}			1.2	2.4	μѕ	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 2.2 \Omega$		5	10		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 4.5 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		14	28		
Fall Time	t _f			10	20		
Turn-On Delay Time	t _{d(on)}			0.5	1		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 2.2 \Omega$		1.4	2.8		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 4.5 A, V_{GEN} = - 10 V, R_g = 1 Ω		20	40		
Fall Time	t _f			10	20		
Drain-Source Body Diode Characterist	cs	,					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.5		
Pulse Diode Forward Current	I _{SM}				- 15	A	
Body Diode Voltage	V_{SD}	I _S = - 4.5 A, V _{GS} = 0 V		- 0.9	- 1.2	V	
lody Diode Reverse Recovery Time t _{rr}				20	40	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 4.5 A, dl/dt = 100 A/μs, T _J = 25 °C		11	20	nC	
Reverse Recovery Fall Time	t_a t_a $t_b = -4.5 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, \text{ f}_J = 25 \text{ C}$			12		20	
Reverse Recovery Rise Time	t _b			8		ns	

Notes:

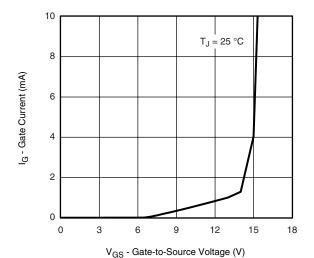
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

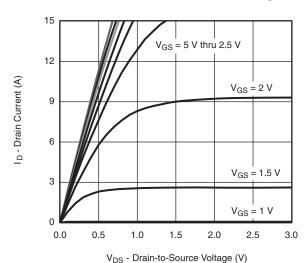
b. Guaranteed by design, not subject to production testing.



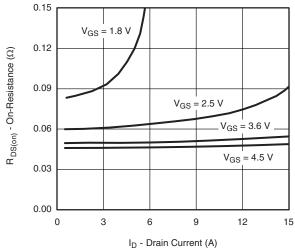
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



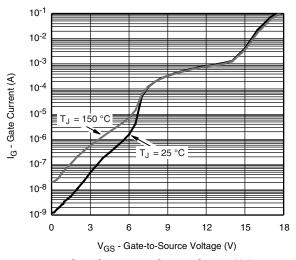
Gate Current vs. Gate-to-Source Voltage



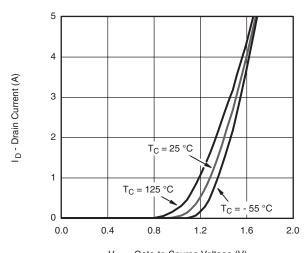
Output Characteristics



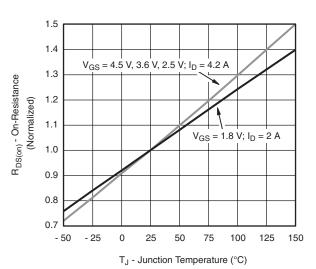
On-Resistance vs. Drain Current



Gate Current vs. Gate-to-Source Voltage



V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**



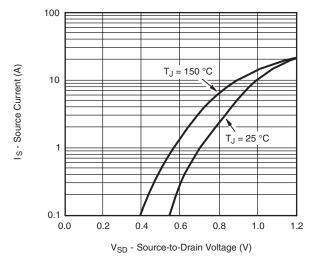
On-Resistance vs. Junction Temperature

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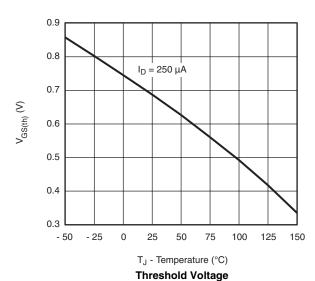
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 $I_D = 2 A; T_J = 125 °C$

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Soure-Drain Diode Forward Voltage



V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage

3

4

5

0.15

0.12

0.09

0.06

0.03

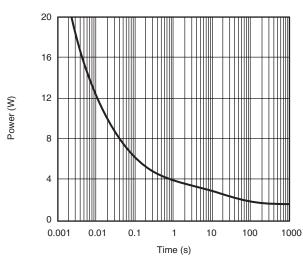
0.00

0

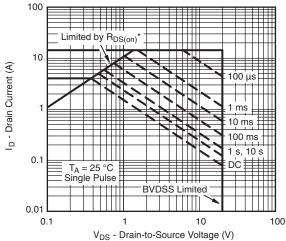
 $I_D = 2 \text{ A}; T_J = 25 \text{ }^{\circ}\text{C}$

I_D = 4.2 A; T_J = 25 °C

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - On-Resistance (Ω)



Single Pulse Power, Junction-to-Ambient



* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

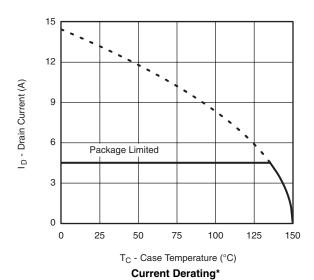
Safe Operating Area, Junction-to-Ambient

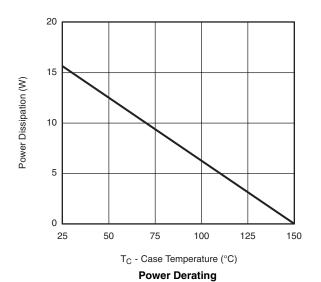




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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

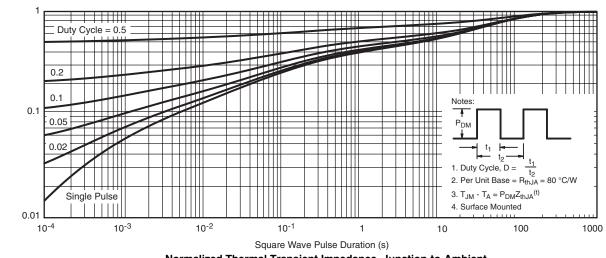
Normalized Effective Transient Thermal Impedance

Normalized Effective Transient Thermal Impedance

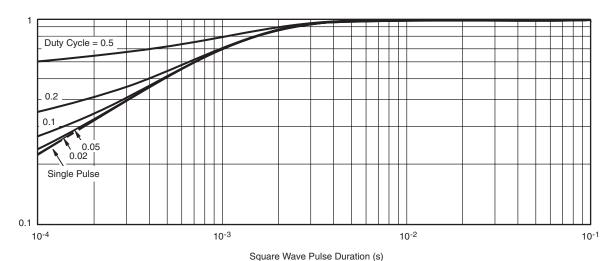
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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